



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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CHO-BOND® 584-208

TWO COMPONENT ELECTRICALLY CONDUCTIVE EPOXY ADHESIVE SYSTEM



Customer Value Proposition:

CHO-BOND 584-208 is a two-component, silver filled conductive epoxy adhesive system designed for applications where a strong, highly conductive electrical bond must be achieved. CHO-BOND 584-208 is recommended for applications which require a conductive epoxy with an extended working life such as high volume part dispensing or complex part assembly operations.

Curing of CHO-BOND 584-208 can be achieved in as little as 45 minutes with heat to minimize equipment downtime and increase manufacturing throughput. With a 1:1 weight mix ratio, CHO-BOND 584-208 is easy to handle and use. Typical applications include bonding and grounding of electrical components, cold soldering, and bonding and sealing machined enclosures.



Features and Benefits:

- Two component
- Silver filler
- Epoxy
- 1:1 Weight mix ratio
- Medium paste
- No VOCs
- Fast heat cure, increases throughput, minimizes equipment downtime.
- Good conductivity 0.002 ohm-cm
- 60 minute working life, works well over wide temperature range, good chemical resistance >1000 psi lap shear, good for permanently bonding surfaces.
- Easy to weigh out and mix.
- May be dispensed out of very small needles, fill small cracks and voids. Can be used on overhead or vertical surfaces
- Minimal shrinkage, no permits or ventilation required

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CHO-BOND 584-208 - Product Information

Table 1 Typical Properties

Typical Properties	Typical Values	Test Method
Polymer	Epoxy	N/A
Filler	Silver	N/A
Mix Ratio, A : B (by weight)	1 : 1	N/A
Color	Silver	N/A (Q)
Consistency	Medium Paste	N/A (Q)
Maximum DC Volume Resistivity (Cure Cycle 1)	0.002 ohm-cm	CHO-95-40-5101* (Q/C)
Minimum Lap Shear Strength (Cure Cycle 1)	1000 psi (6895 kPa)	CHO-95-40-5300* (Q/C)
Specific Gravity (Room Temp Cure)	2.6	ASTM D792 (Q/C)
Hardness (Cure Cycle 1)	80 Shore D	ASTM-D2240 (Q)
Continuous Use Temperature	- 62°C to 100°C (-80°F to 212°F)	N/A (Q)
Elevated Temperature Cure Cycle	Cure Cycle Option 1: 0.75 hour @ 100°C (212°F) Cure Cycle Option 2: 2.0 hours @ 65°C (150°F)	N/A
Room Temperature Cure	24 hours	N/A (Q)
Working Life	1.0 hours	N/A (Q)
Shelf Life, unopened	9 months @ 25°C (77°F)	N/A (Q)
Minimum thickness recommended	0.001 in (0.03 mm)	N/A
Maximum thickness recommended	None	N/A
Volatile Organic Content (VOC)	0 g/l	Calculated
Typical Coverage Area at 0.010" Thick per Pound (454 grams)	10,500 in ² (67,742 cm ²)	N/A

Note: N/A – Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test

* This test Method is available from Parker Chomerics.

Table 2 Ordering Information

Product	Weight (grams)	Packaging	Part Number	Primer Included
CHO-BOND 584-208	85	2 component, 4 fluid ounce polypropylene kit	50-00-0584-0208	Not required
	454	2 component, 16 fluid ounce polypropylene kit	50-01-0584-0208	Not required

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

www.chomerics.com

www.parker.com/chomerics

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